Technical Data Sheet（TDS）

8621 SMT(surface mount technology) Adhesive

Product description：

8621 is a one component heat curing epoxy adhesive. Suitable for screen printing. This product has excellent heat resistance, excellent moisture resistance and adhesion strength, electrical properties, has good storage stability.

Typical application：

Mainly used for STM bonding components.

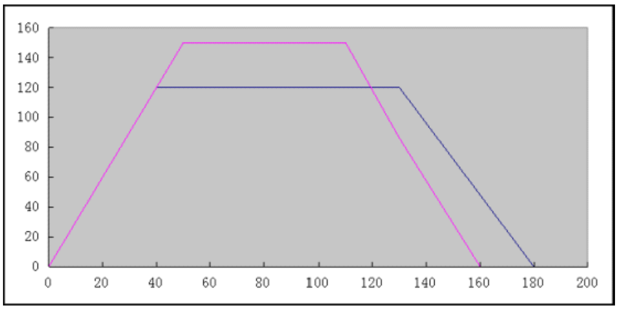
Typical properties：

Chemical composition: epoxy resin
color： red paste

Main parameter	Typical	range
Density (g/cm^3)	1.35	1.3-1.4
viscosity (mPa.s@25℃)	350000	250000-450000

Recommend cure condition：

120℃ 90-120s or 150℃ 60-90s



Higher curing temperatures and longer curing time will get a better bond strength.
The curves for the recommended curing temperature and heating rate, show when the components reach a good adhesion needs time at the corresponding temperature. Users can set the oven temperature according the curing curves and oven efficiency.

Properties after curing：

(sample curing at 150℃ 30min)

Main parameter	Typical	range
Hardness（Shore D）	82	
Elongation at break (%)		≤4
Shear strength (MPa)	15.3	≥10
Tg(℃)(DSC)	102	

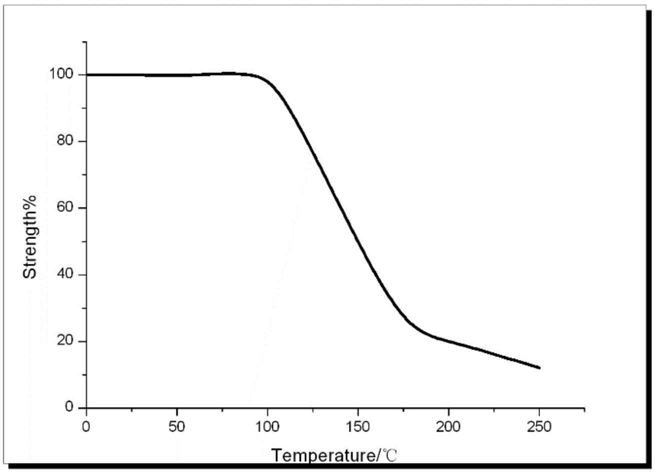
Electric properties：

Volume resistivity ASTM D149,Ω·cm	3.7×10^{14}	
Surface resistivity ASTM D149, Ω	7.5×10^{14}	
Dielectric strength ASTM 257,KV/m	20	

Heat-resisting strength

(sample curing at 150℃ 30min)

AL/AL shear strength（under appropriate temperature test）



Store：

2~8℃ dry sealed storage, shelf life is 6 months.

Direction for use：

1. Before using the adhesive must be returned to room temperature, before return the room temperature （300ml package, normally takes 2-4h）,don’t open the package to prevent adsorption of moisture in the air and affect the using.
2. Recommendation printing condition is 25℃ relative humidity less than 60%. High temperature will decline the viscosity to affect the printing effect; high humidity will increase adsorption to short opening hours and affect the final bonding strength. At the 25℃, relative humidity 55%, this product opening time is 48h.
3. Recommendation printing speed 20-150mm/s ；scraper force 3-4N/cm(after scraper scratch, stencil relatively clean, avoid to produce wiredrawing)；Take off the plate speed is 0.1-3.0mm/s。
4. Use acetone or glycol ethers to wipe the uncured adhesive on the circuit board.

5. Unused adhesive, first seal and then place in the refrigerator for storage.

Notice：

1. Away from children
2. Using this product in a well-ventilated place
3. If accidentally touch into the skin, please immediately wash with soap and water.
4. If the eyes, please use amount water to wash, and the go to the doctor.

Technical Service：

If other problems encountered in use, please contact the ASI Technologies technical services department.

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